Product Change Notification

111822 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Change Notification #:	**111822 - 00**
Change Title:	**Intel® Server Chassis H2216XXJR and H2312XXJR Intel® Server System H2216JFFJR, H2216JFJR, H2216JFQJR, H2216LPJR, H2216WPFJR, H2216WPJR, H2216WPQJR, H2312JFFJR, H2312JFJR, H2312JFQJR, H2312LPJR, H2312WPFJR, H2312WPJR and H2312WPQJR PCN 111822-00, Product Design Chassis Mechanical Changes**
Date of Publication:	**October 31, 2012**

Key Characteristics of the Change:

Product Design

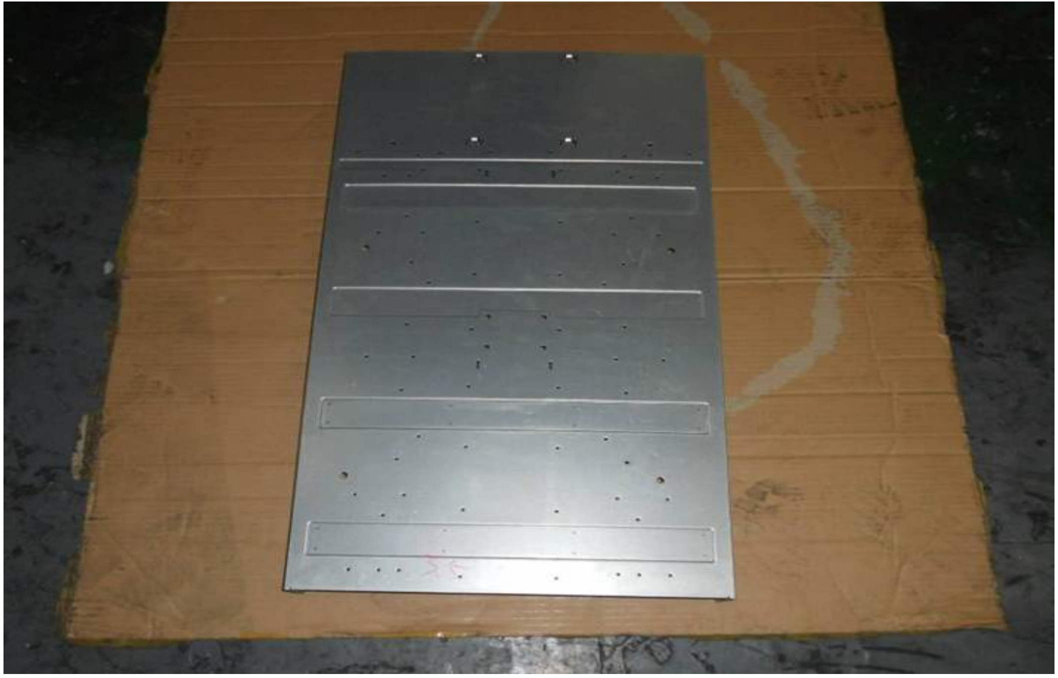
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 15, 2012

Description of Change to the Customer:

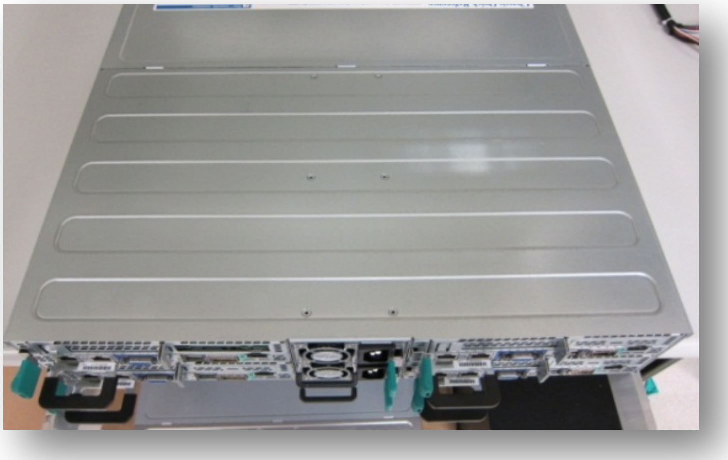
The Chassis base architecture has been strengthened to resolve an issue where the middle of the chassis may sag when the system is installed in a rack.

1. Added 4 emboss areas on the chassis base (see picture below).



2. The chassis will be pre-bent in the opposite direction that the chassis may sag, when installed in a rack. The chassis will show a slight horizontal bow when empty, but will be completely horizontal when all modules and other items are installed in it.

3. Added an emboss area on the rear top cover (see picture below).



Customer Impact of Change and Recommended Action:

Intel suggests customers evaluate the new chassis material when made available.

Products Affected / Intel Ordering Codes:

Product Code	MM#	TA
H2312JFJR	918305	G51225-001
H2312JFQJR	918306	G51229-001
H2216JFJR	918307	G51236-001
H2216JFQJR	918308	G51240-001
H2312LPJR	919008	G61032-001
H2216LPJR	919014	G61038-001
H2312WPJR	919016	G54620-001
H2312WPQJR	919017	G54623-001
H2216WPJR	919018	G54626-001
H2216WPQJR	919019	G54629-001
H2312XXJR	919020	G51243-001
H2216XXJR	919021	G51246-001
H2312JFFJR	921303	G58683-002
H2216JFFJR	921304	G58686-002
H2312WPFJR	921315	G58689-001
H2216WPFJR	921316	G58692-001

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
October 31, 2012	00	Originally Published PCN